

DATA SHEET



GaAs INTEGRATED CIRCUIT μ PG2179TB

L, S-BAND MEDIUM POWER SPDT SWITCH

DESCRIPTION

The μ PG2179TB is a GaAs MMIC L, S-band SPDT (Single Pole Double Throw) switch for mobile phone and other L, S-band applications. This device operates with dual control voltages of 2.5 to 5.3 V. This device can operate from 0.05 to 3.0 GHz, with low insertion loss and high isolation.

This device is housed in a 6-pin super minimold package, and is suitable for high-density surface mounting.

★ FEATURES

- Switch control voltage : $V_{\text{cont (H)}} = 2.5 \text{ to } 5.3 \text{ V (3.0 V TYP.)}$
: $V_{\text{cont (L)}} = -0.2 \text{ to } +0.2 \text{ V (0 V TYP.)}$
- Low insertion loss : $L_{\text{ins1}} = 0.25 \text{ dB TYP. @ } f = 0.05 \text{ to } 1.0 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
: $L_{\text{ins2}} = 0.30 \text{ dB TYP. @ } f = 1.0 \text{ to } 2.0 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
: $L_{\text{ins3}} = 0.35 \text{ dB TYP. @ } f = 2.0 \text{ to } 2.5 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
: $L_{\text{ins4}} = 0.40 \text{ dB TYP. @ } f = 2.5 \text{ to } 3.0 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
- High isolation : $ISL1 = 27 \text{ dB TYP. @ } f = 0.05 \text{ to } 2.0 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
: $ISL2 = 24 \text{ dB TYP. @ } f = 2.0 \text{ to } 3.0 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
- Power handling : $P_{\text{in (0.1 dB)}} = +29.0 \text{ dBm TYP. @ } f = 0.5 \text{ to } 3.0 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
: $P_{\text{in (1 dB)}} = +32.0 \text{ dBm TYP. @ } f = 0.5 \text{ to } 3.0 \text{ GHz, } V_{\text{cont (H)}} = 3.0 \text{ V, } V_{\text{cont (L)}} = 0 \text{ V}$
- High-density surface mounting : 6-pin super minimold package (2.0 × 1.25 × 0.9 mm)

APPLICATIONS

- L, S-band digital cellular or cordless telephone
- PCS, W-LAN, WLL and Bluetooth™ etc.

★ ORDERING INFORMATION

Part Number	Package	Marking	Supplying Form
μ PG2179TB-E4	6-pin super minimold	G4C	<ul style="list-style-type: none">• Embossed tape 8 mm wide• Pin 4, 5, 6 face the perforation side of the tape• Qty 3 kpcs/reel

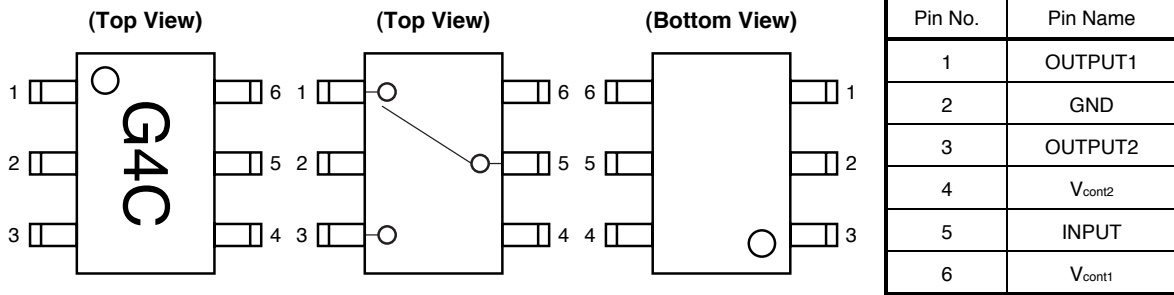
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: μ PG2179TB-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



TRUTH TABLE

V _{cont1}	V _{cont2}	INPUT-OUTPUT1	INPUT-OUTPUT2
Low	High	ON	OFF
High	Low	OFF	ON

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	V _{cont}	6.0 ^{Note}	V
Input Power	P _{in}	+33	dBm
Operating Ambient Temperature	T _A	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

★ **Note** |V_{cont1} - V_{cont2}| ≤ 6.0 V

RECOMMENDED OPERATING RANGE (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
★ Switch Control Voltage (H)	V _{cont (H)}	2.5	3.0	5.3	V
Switch Control Voltage (L)	V _{cont (L)}	-0.2	0	0.2	V

★ **ELECTRICAL CHARACTERISTICS**

(T_A = +25°C, V_{cont} (H) = 3.0 V, V_{cont} (L) = 0 V, DC blocking capacitors = 100 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L _{ins1}	f = 0.05 to 1.0 GHz ^{Note1}	-	0.25	0.45	dB
Insertion Loss 2	L _{ins2}	f = 1.0 to 2.0 GHz	-	0.30	0.50	dB
Insertion Loss 3	L _{ins3}	f = 2.0 to 2.5 GHz	-	0.35	0.55	dB
Insertion Loss 4	L _{ins4}	f = 2.5 to 3.0 GHz	-	0.40	0.60	dB
Isolation 1	ISL1	f = 0.05 to 2.0 GHz ^{Note1}	23	27	-	dB
Isolation 2	ISL2	f = 2.0 to 3.0 GHz	20	24	-	dB
Input Return Loss	RL _{in}	f = 0.05 to 3.0 GHz ^{Note1}	15	20	-	dB
Output Return Loss	RL _{out}	f = 0.05 to 3.0 GHz ^{Note1}	15	20	-	dB
0.1 dB Loss Compression Input Power ^{Note2}	P _{in (0.1 dB)}	f = 2.0 GHz	+25.5	+29.0	-	dBm
		f = 2.5 GHz	+25.5	+29.0	-	dBm
		f = 0.5 to 3.0 GHz	-	+29.0	-	dBm
Switch Control Current	I _{cont}	No signal	-	4	20	μA
Switch Control Speed	t _{sw}	50%CTL to 90/10%RF	-	50	500	ns

Note1. DC blocking capacitor = 1 000 pF at f = 0.05 to 0.5 GHz.

2. P_{in (0.1 dB)} is the measured input power level when the insertion loss increases 0.1 dB more than that of linear range.

★ **STANDARD CHARACTERISTICS FOR REFERENCE**

(T_A = +25°C, V_{cont} (H) = 3.0 V, V_{cont} (L) = 0 V, DC blocking capacitors = 100 pF, unless otherwise specified)

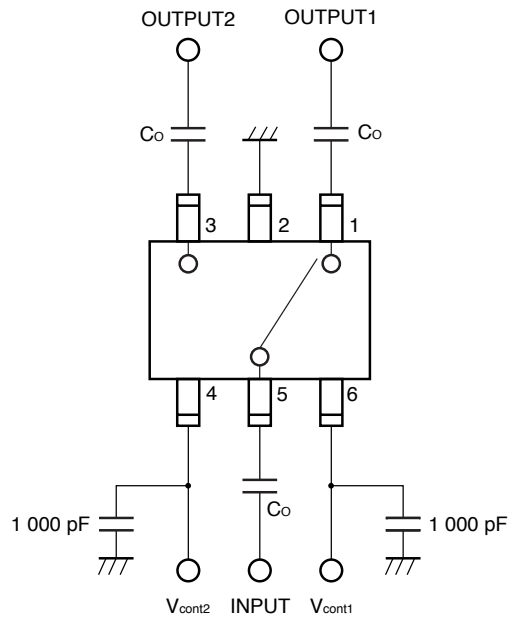
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
1 dB Loss Compression Input Power ^{Note}	P _{in (1 dB)}	f = 0.5 to 3.0 GHz	-	+32.0	-	dBm
3rd Order Intermodulation Intercept Point	IIP ₃	f = 0.5 to 3.0 GHz, 2 tone, 5 MHz spacing	-	+60.0	-	dBm

Note P_{in (1 dB)} is the measured input power level when the insertion loss increases 1 dB more than that of linear range.

★ **Caution** When using this IC, a DC coupling capacitor must be externally attached to the I/O pins.

A DC coupling capacitor with a capacitance of 100 pF or lower is recommended when using a frequency of 0.5 GHz or higher, and one with a capacitance of 1,000 pF is recommended when using a frequency of less than 0.5 GHz. The ideal value changes depending on the frequency and bandwidth used, so select a capacitor with a suitable capacitance according to the usage conditions.

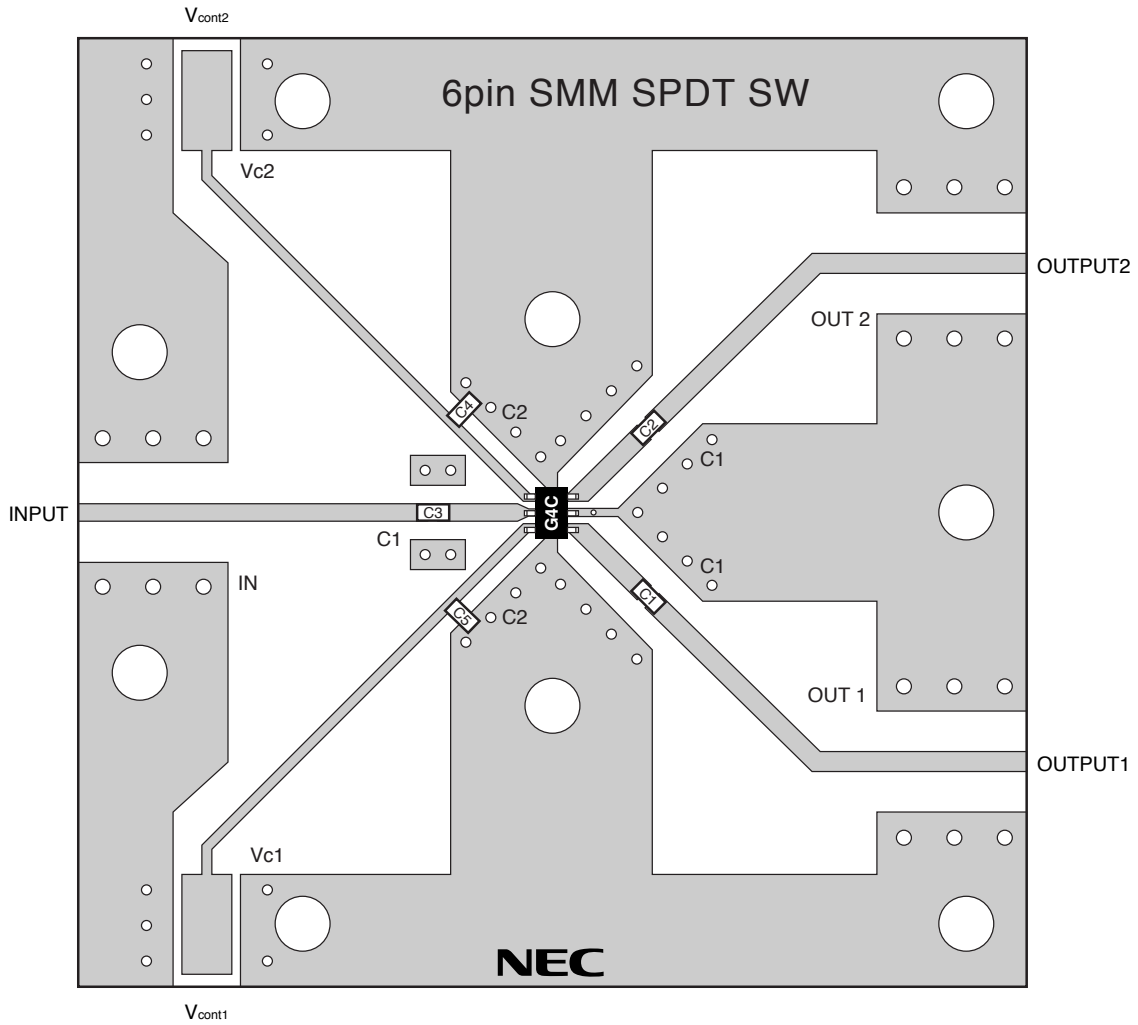
★ EVALUATION CIRCUIT



Remark C_o : 0.05 to 0.5 GHz 1 000 pF
 0.5 to 3.0 GHz 100 pF

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

★ ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

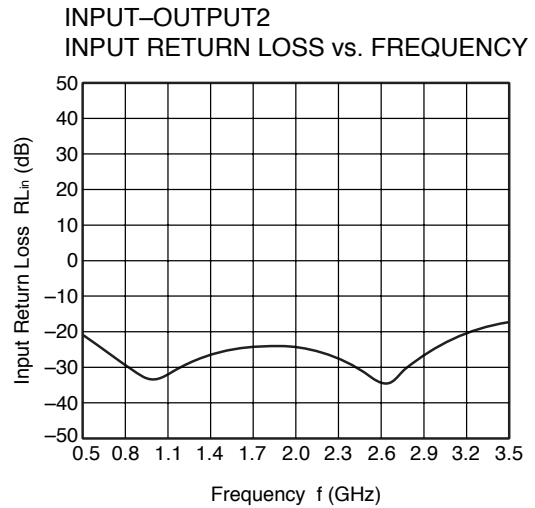
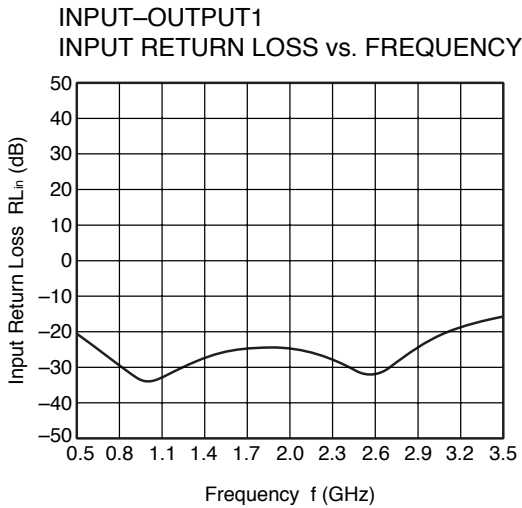
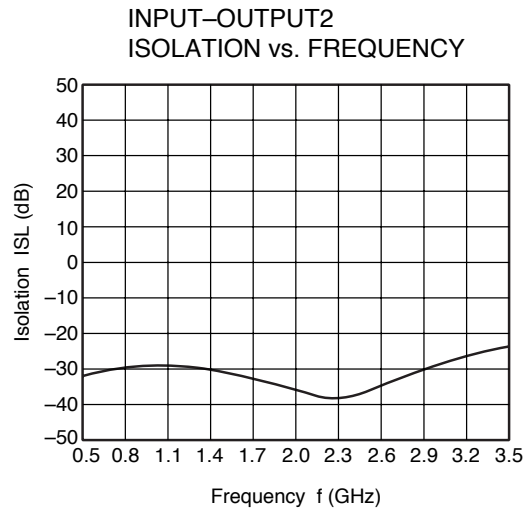
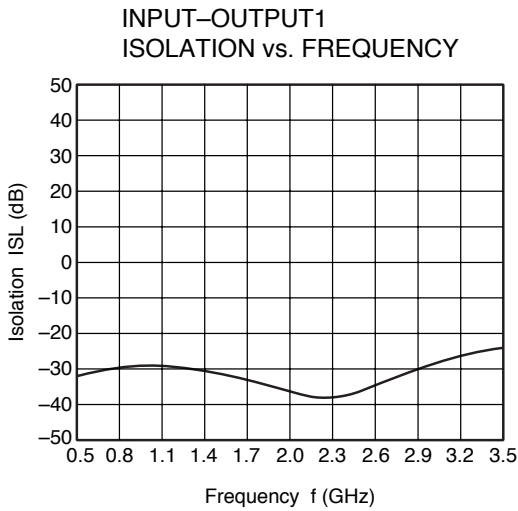
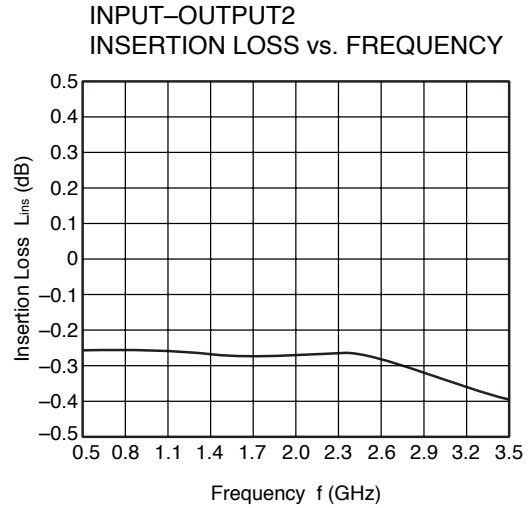
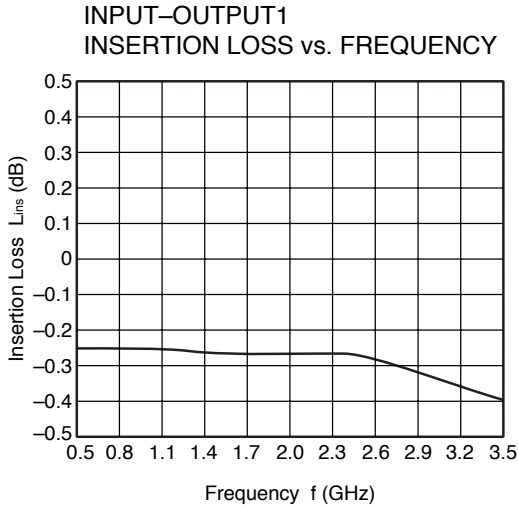


USING THE NEC EVALUATION BOARD

Symbol	Values
C1, C2, C3	100 pF
C4, C5	1 000 pF

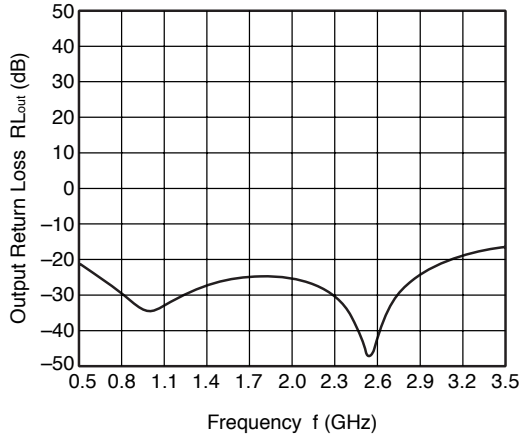
TYPICAL CHARACTERISTICS

★ (T_A = +25°C, V_{cont} (H) = 3.0 V, V_{cont} (L) = 0 V, DC blocking capacitors = 100 pF, unless otherwise specified)

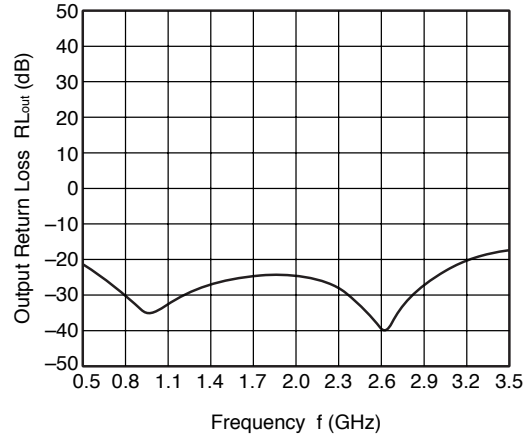


Remark The graphs indicate nominal characteristics.

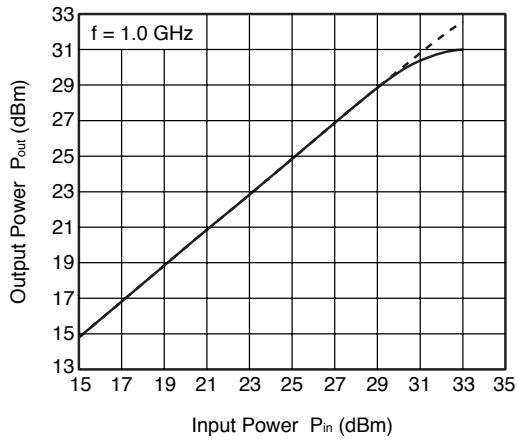
INPUT-OUTPUT1
OUTPUT RETURN LOSS vs. FREQUENCY



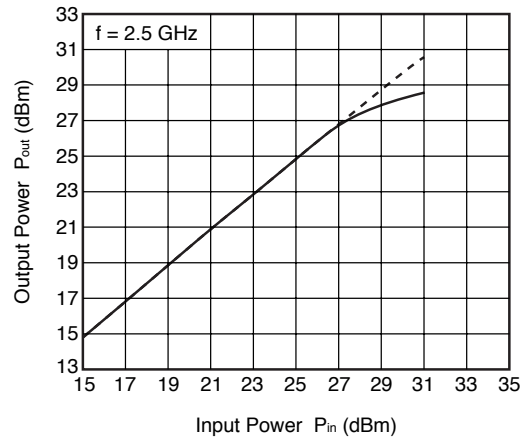
INPUT-OUTPUT2
OUTPUT RETURN LOSS vs. FREQUENCY



OUTPUT POWER vs. INPUT POWER



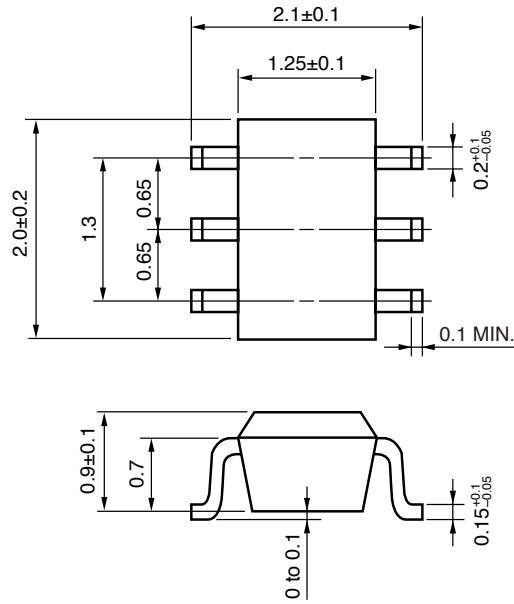
OUTPUT POWER vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

PACKAGE DIMENSIONS

6-PIN SUPER MINIMOLD (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) : 215°C or below Time at temperature of 200°C or higher : 25 to 40 seconds Preheating time at 120 to 150°C : 30 to 60 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 00.4-0110

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► For further information, please contact

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